TLP240D,TLP240DF

1. Applications

- Mechanical relay replacements
- Security Systems
- Measuring Instruments
- Factory Automation (FA)
- Amusement Equipment
- Smart Meters
- Electricity Meters

2. General

The TLP240D and TLP240DF photorelay consist of a photo MOSFET optically coupled to an infrared light emitting diode. They are housed in a 4-pin DIP package. They provide an isolation voltage of 5000 Vrms, making them suitable for applications that require reinforced insulation.

3. Features

- (1) Halogen-free
- (2) Normally opened (1-Form-A)
- (3) OFF-state output terminal voltage: 200 V (min)
- (4) Trigger LED current: 3 mA (max)
- (5) ON-state current: 250 mA (max)
- (6) ON-state resistance: 8Ω (max)
- (7) Isolation voltage: 5000 Vrms (min)
- (8) Safety standards

UL-approved: UL1577, File No.E67349

cUL-approved: CSA Component Acceptance Service No.5A File No.E67349

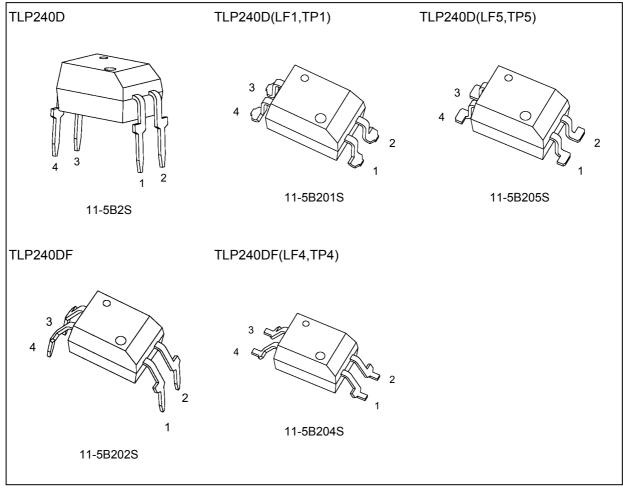
- VDE-approved: EN60747-5-5 (Note 1)
- CQC-approved: GB4943.1, GB8898 Japan Factory

Note 1: When an EN60747-5-5 approved type is needed, please designate the Option (D4).

4. Mechanical Parameters

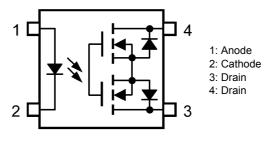
Characteristics	7.62-mm Pitch TLP240D	10.16-mm Pitch TLP240DF	Unit
Creepage distances	7.0 (min)	8.0 (min)	mm
Clearance distances	7.0 (min)	8.0 (min)	
Internal isolation thickness	0.4 (min)	0.4 (min)	

5. Packaging (Note)

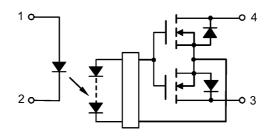


Note: Through-hole type: TLP240D, TLP240DF Lead forming option: (LF1), (LF4), (LF5) Taping option: (TP1), (TP4), (TP5)

6. Pin Assignment



7. Internal Circuit



8. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Rating	Unit	
LED	Input forward current		l _F		30	mA
	Input forward current derating	(T _a ≥ 25 °C)	$\Delta I_F / \Delta T_a$		-0.3	mA/°C
	Input forward current (pulsed)	(100 µs pulse, 100 pps)	I _{FP}		1	A
	Input reverse voltage		V _R		5	V
	Input power dissipation		PD		50	mW
	Junction temperature		Тj		125	°C
Detector	OFF-state output terminal voltage		V _{OFF}		200	V
	ON-state current		I _{ON}		250	mA
	ON-state current derating	$(T_a \ge 25 \ ^\circ C)$	$\Delta I_{ON} / \Delta T_a$		-2.5	mA/°C
	ON-state current (pulsed)	(t = 100 ms, Duty = 1/10)	I _{ONP}		750	mA
	Output power dissipation		Po		500	mW
	Junction temperature		Тj		125	°C
Common	Storage temperature		T _{stg}		-55 to 125	°C
	Operating temperature		T _{opr}		-40 to 85	°C
	Lead soldering temperature	(10 s)	T _{sol}		260	°C
	Isolation voltage	AC, 60 s, R.H. \leq 60 %	BVS	(Note 1)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

9. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Тур.	Max	Unit
Supply voltage	V _{DD}		_	_	160	V
Input forward current	١ _F		5	7.5	25	mA
ON-state current	I _{ON}		_	—	250	mA
Operating temperature	T _{opr}		-20	_	65	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

10. Electrical Characteristics (Unless otherwise specified, $T_a = 25$ °C)

	Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
LED	Input forward voltage	V _F		I _F = 10 mA	1.1	1.27	1.4	V
	Input reverse current	I _R		V _R = 5 V	_		10	μA
	Input capacitance	Ct		V = 0 V, f = 1 MHz	_	50	_	pF
Detector	OFF-state current	I _{OFF}		V _{OFF} = 200 V	_	_	1000	nA
	Output capacitance	C _{OFF}		V = 0 V, f = 1 MHz	_	80		pF

11. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Trigger LED current	I _{FT}		I _{ON} = 250 mA	_	0.6	3	mA
Return LED current	I _{FC}		I _{OFF} = 10 μA	0.1	_	—	
ON-state resistance	R _{ON}	(Note 1)	I_{ON} = 250 mA, I_F = 5 mA, Continuous	_	5	8	Ω

Note 1: Thermally saturated state.

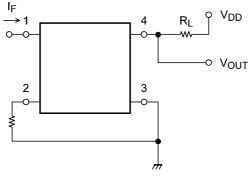
12. Isolation Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Note Test Condition		Тур.	Max	Unit
Total capacitance (input to output)	Cs	(Note 1)	V _S = 0 V, f = 1 MHz	—	0.8	_	pF
Isolation resistance	R _S	(Note 1)	V_S = 500 V, R.H. \leq 60 %	1 × 10 ¹²	1014	_	Ω
Isolation voltage	BVS	(Note 1)	(Note 1) AC, 60 s			_	Vrms
			AC, 1 s in oil	—	10000	—	
			DC, 60 s in oil	_	10000	_	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

13. Switching Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Turn-on time	t _{ON}		See Fig. 13.1.	_	1	3	ms
Turn-off time	t _{OFF}		R_{L} = 200 Ω, V_{DD} = 20 V, I_{F} = 5 mA		0.1	1	



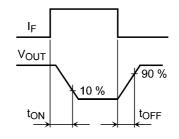
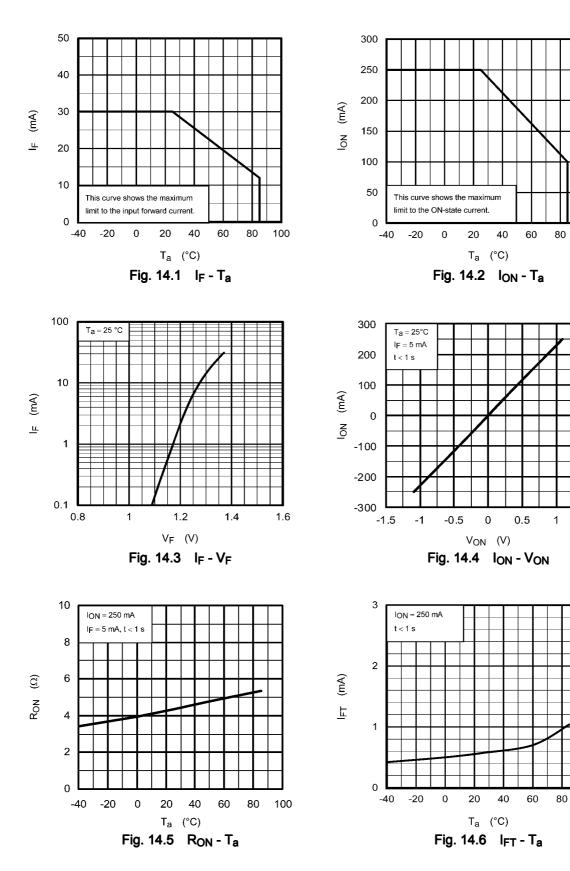


Fig. 13.1 Switching Time Test Circuit

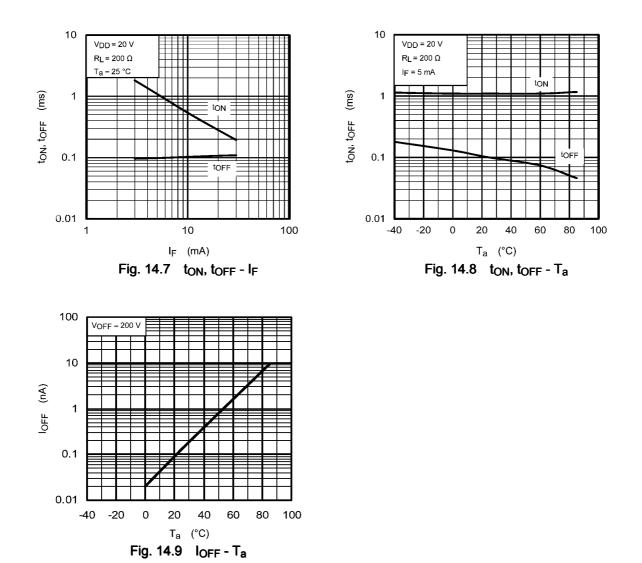
100

1.5

14. Characteristics Curves (Note)



100



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

15. Soldering and Storage

15.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

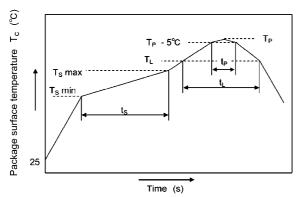
• When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	s
Ramp-up rate (T_L to T_P)			3	°C/s
Liquidus temperature	TL	217		°C
Time above T_L	tL	60	150	S
Peak temperature	Τ _Ρ		260	°C
Time during which T_c is between (T _P – 5) and T _P	t₽		30	S
Ramp-down rate $(T_P \text{ to } T_L)$			6	°C/s

Fig. 15.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

 When using soldering flow Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds. Mounting condition of 260 °C within 10 seconds is recommended.

Flow soldering must be performed once.

• When using soldering Iron

Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C

Heating by soldering iron must be done only once per lead.

15.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

1.6

16. Land Pattern Dimensions (for reference only)

Unit: mm

TLP240D

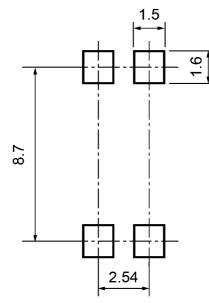
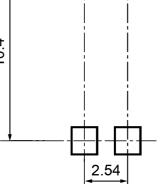
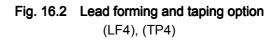


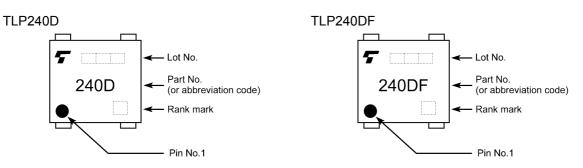
Fig. 16.1 Lead forming and taping option (LF1), (TP1), (LF5), (TP5)

TLP240DF





17. Marking (Note)



Note: A different marking is used for photocouplers that have been qualified according to option (D4) of EN60747. See Fig.18.3 and Fig.18.4.

18. EN60747-5-5 Option (D4) Specification

- Part number: TLP240D (Note 1)
- The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN60747.

Example: TLP240D(D4,TP1,F(O

D4: EN60747 optionTP1: Tape typeF: [[G]]/RoHS COMPATIBLE (Note 2)O: Domestic ID (Country/Region of origin: Japan)

Note 1: Use TOSHIBA standard type number for safety standard application. e.g., TLP240D(D4,TP1,F(O \rightarrow TLP240D

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

Description	Symbol	Rating	Unit		
Application classification	Application classification				
for rated mains voltage \leq 300 Vrms for rated mains voltage \leq 600 Vrms			I-IV I-III	_	
Climatic classification			40 / 085 / 21	-	
Pollution degree			2	_	
		890			
Maximum operating insulation voltage	TLPxxxxF type	VIORM	1130	Vpeak	
Input to output test voltage, Method A	TLPxxxx type	- V _{pr}	1424	Vpeak	
V_{pr} = 1.6 \times $V_{IORM},$ type and sample test t_p = 10 s, partial discharge $<$ 5 pC	TLPxxxxF type		1808		
Input to output test voltage, Method B	TLPxxxx type		1670	Manak	
V_{pr} = 1.875 × V_{IORM} , 100 % production test t_p = 1 s, partial discharge < 5 pC	TLPxxxxF type	- V _{pr}	2120	Vpeak	
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)		V _{TR}	8000	Vpeak	
Safety limiting values (max. permissible ratings in case also refer to thermal derating of current (input current I _F , P _{so} = 0) power (output or total power dissipation) temperature	I _{si} P _{so} T _s	400 700 150	mA mW °C		
Insulation resistance $V_{IO} = 500 \text{ V}, \text{ T}_a = 25 \text{ °C}$ $V_{IO} = 500 \text{ V}, \text{ T}_a = 100 \text{ °C}$ $V_{IO} = 500 \text{ V}, \text{ T}_a = \text{ T}_s$	R _{si}	$\ge 10^{12}$ $\ge 10^{11}$ $\ge 10^{9}$	Ω		

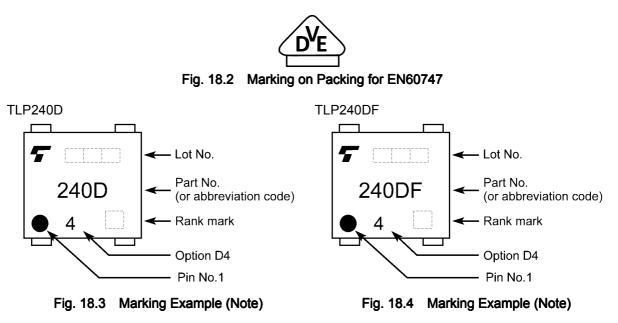
Fig. 18.1 E	N60747 Insulation	Characteristics
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Insulation Related Parameters	Symbol	TLP240D	TLP240DF
Minimum creepage distance	Cr	7.0 mm	8.0 mm
Minimum clearance	CI	7.0 mm	8.0 mm
Minimum insulation thickness	ti	0.4 mm	0.4 mm
Comparative tracking index	СТІ	175	175

Table 18.1	Insulation Related Specification	ns (Note)
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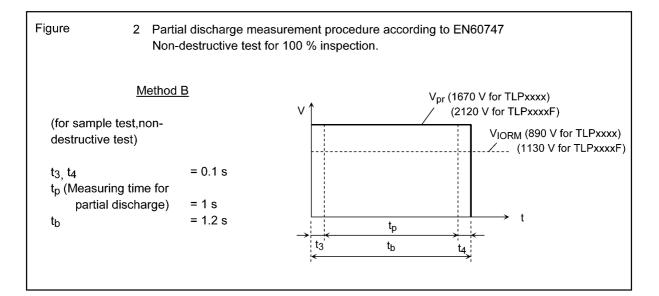
Note: If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. (e.g., at a standard distance between soldering eye centers of 7.5 mm). If this is not permissible, the user shall take suitable measures.

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN60747.

	•	asurement procedure according to EN60747 Jalification and sampling tests.
Method	<u>A</u>	VINITIAL (8 kV)
(for type and sampling destructive tests)	tests,	V V V V V V V V V V V V V V V V V V V
t ₁ , t ₂	= 1 to 10 s	V _{IORM} (890 V for TLPxxxx)
t3, t4	= 1 s	(1130 V for TLPxxxxF)
t _p (Measuring time for		
partial discharge)	= 10 s	$0 \xrightarrow{l} t \xrightarrow{l} t$
t _b	= 12 s	t_3 t_p t_4
t _{ini}	= 60 s	t_1 t_{ini} t_2 t_b



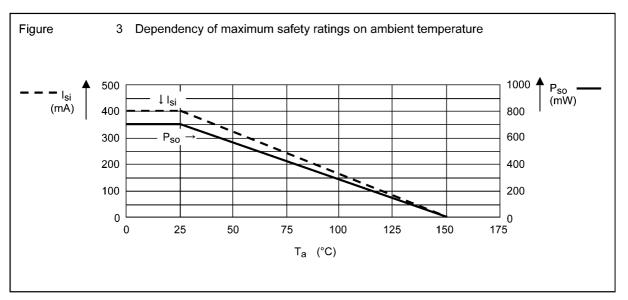


Fig. 18.5 Measurement Procedure

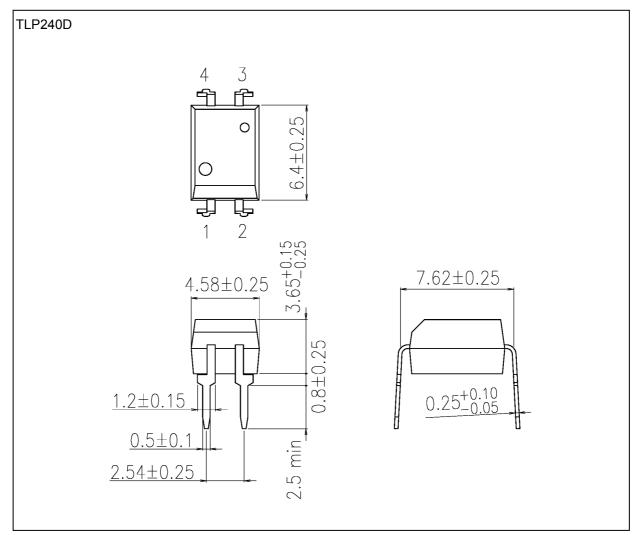
19. Ordering Information (Example of Item Name)

Item Name	Packaging (Note 1)	VDE Option	Packing (MOQ)
TLP240D(F(O	ТН		Magazine (100 pcs)
TLP240D(LF1,F(O	LF1		Magazine (100 pcs)
TLP240D(LF5,F(O	LF5		Magazine (100 pcs)
TLP240D(TP1,F(O	TP1		Tape and reel (1500 pcs)
TLP240D(TP5,F(O	TP5		Tape and reel (1500 pcs)
TLP240D(D4,F(O	TH	EN60747-5-5	Magazine (100 pcs)
TLP240D(D4,LF1,F(O	LF1	EN60747-5-5	Magazine (100 pcs)
TLP240D(D4,LF5,F(O	LF5	EN60747-5-5	Magazine (100 pcs)
TLP240D(D4,TP1,F(O	TP1	EN60747-5-5	Tape and reel (1500 pcs)
TLP240D(D4,TP5,F(O	TP5	EN60747-5-5	Tape and reel (1500 pcs)
TLP240DF(F(O	TH, Wide forming		Magazine (100 pcs)
TLP240DF(LF4,F(O	LF4, Wide forming		Magazine (100 pcs)
TLP240DF(TP4,F(O	TP4, Wide forming		Tape and reel (1000 pcs)
TLP240DF(D4,F(O	TH, Wide forming	EN60747-5-5	Magazine (100 pcs)
TLP240DF(D4LF4,F(O	LF4, Wide forming	EN60747-5-5	Magazine (100 pcs)
TLP240DF(D4TP4,F(O	TP4, Wide forming	EN60747-5-5	Tape and reel (1000 pcs)

Note 1: TH: Through-hole, LF/TP: Lead forming for surface mount

Package Dimensions

Unit: mm

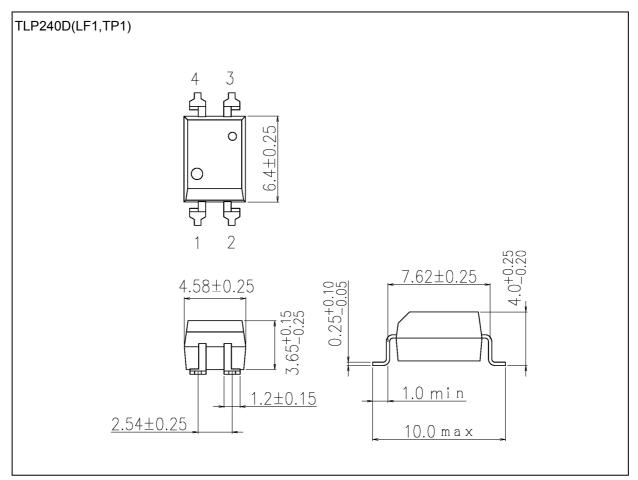


Weight: 0.26 g (typ.)

	Package Name(s)
TOSHIBA: 11-5B2S	



Unit: mm



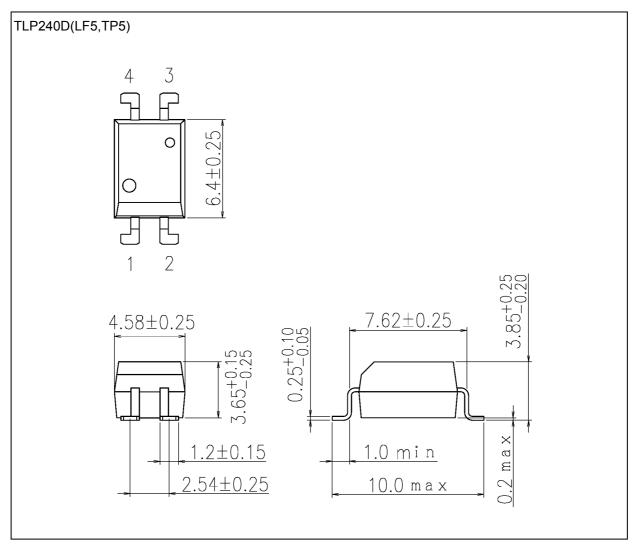
Weight: 0.25 g (typ.)

Package Name(s)

TOSHIBA: 11-5B201S



Unit: mm

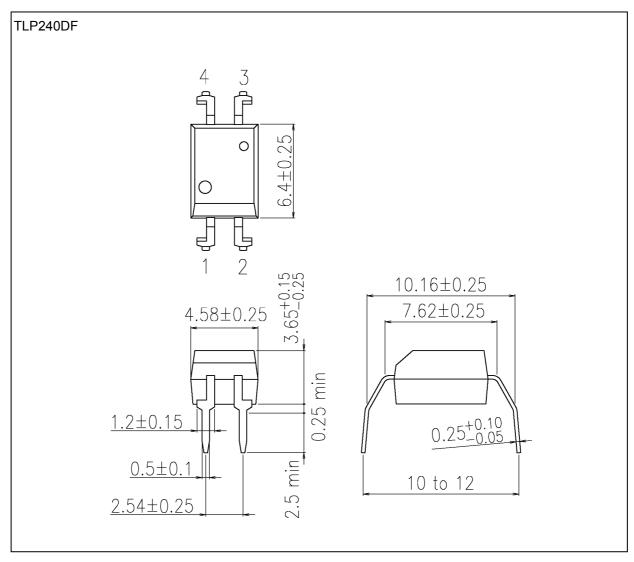


Weight: 0.25 g (typ.)

Package Name(s) TOSHIBA: 11-5B205S



Unit: mm

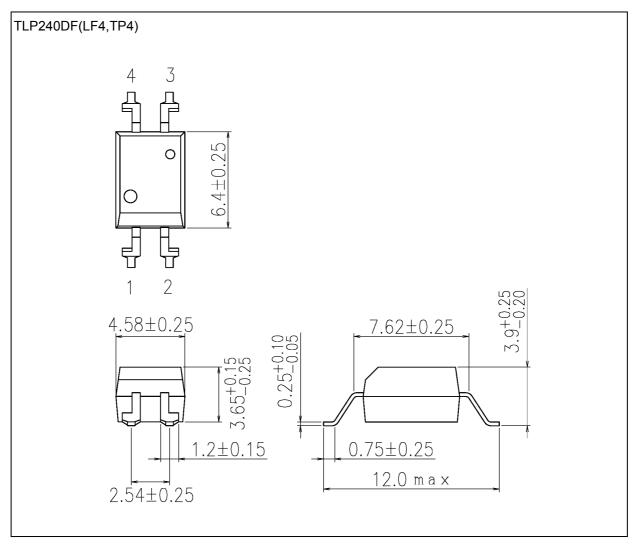


Weight: 0.26 g (typ.)

	Package Name(s)	
TOSHIBA: 11-5B202S		



Unit: mm



Weight: 0.25 g (typ.)

Package Name(s) TOSHIBA: 11-5B204S

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